

Description	 The iT4031F is a RoHS-6-compliant, ultra-wideband phase delay fabricated using 1-um HBT GaAs technology and is based on ECL topology to guarantee high-speed operation. The high output voltage, excellent rise and fall time, and the high eye diagram quality at data rates to 12.5 Gb/s makes the iT4031F is suitable for timing adjustment in data and clock distribution at very high speed. Complex digital applications benefit from the iT4031F, including clock data recovery, edge detectors, NRZ-to-RZ converters, MUX/DEMUX, and data restoration. The device features a single delay element that provides up to 100-ps delay. Delay control can be either differential (using both VCp and VCm) or single-ended (VCm is the active control pad while VCp is shorted to VCref). The control voltage range for the delay input is from -2.2 V to -3.0 V whether the control is single-ended or differential. The device can delay NRZ streams with data rates to 12.5 Gb/s or a clock signal up to 10.7 GHz. Both inputs and outputs are DC-coupled. The iT4031F uses SCFL I/O levels and is designed so to allow for either single ended or differential data input.
Features	 Ultra wideband: Up to 12.5 Gb/s NRZ Delay adjustment to 100 ps 900 mVpp single-ended output Jitter degradation RMS: <1.5 ps Output rise time (20% - 80 %):25 ps typical Output fall time (20% - 80 %): 23 ps typical Differential or single-ended I/O Power consumption: 1.65 W Output impedance: 300 ohms RoHS-6 compliant 5x5-mm QFN (MO-220) package
Device Diagram	DIN DIN DIN/ DIN/ VCm VCp VCref
Timing Diagram	DIN V_{IH} V_{IL} V_{OH} V_{OL} V_{OL} V_{OL} T_{ADJ} T_{ADJ} T_{ADJ} T_{ADJ} T_{ADJ} T_{ADJ} T_{ADJ} T_{ADJ} T_{ADJ} T_{ADJ}
www.iterrac.com	This is a Production data sheet. See "Product Status Definitions" on Web site or catalog for product development status.iTerra Communications 2400 Geng Road, Ste. 100, Palo Alto, CA 94303 Phone (650) 424-1937, Fax (650) 424-1938December 11, 2006Doc. 4093Rev 1.51



Absolute Maximum Ratings

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational section of this document is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Recommended Operating Conditions

Symbol	Parameters/conditions	Min.	Max.	Units	
VEE	Power supply voltage	-5.5	0	V	
VIH	Input voltage level, high level	-1.5	1.5	V	
VIL	Input voltage level, low level	-1.5	1.5	V	
VC	Delay control voltage	-5.0	0	V	
ТА	Operating temperature range – die	-15	125	°C	
TSTG	Storage temperature	-65	150	°C	

Symbol	Parameters/conditions	Min.	Тур.	Max	Units
T _A	Operating temperature range – die	0		85	°C
V _{EE}	Power supply voltage		-5		V
VC	Delay control voltage	-3.0	-2.6	-2.2	V
V _{IH}	Input voltage level, high level (single ended)		0.0		V
V _{IL}	Input voltage level, low level (single ended)		-0.9		V
V _{INDC}	DC input voltage (with DC-coupled input)		-0.45		V

Electrical						
Characteristics	Symbol	Parameters	Min.	Тур.	Max.	Units
	VEE	Power supply voltage	-4.5	-5.00	-5.25	V
1. Electrical	VIH	Input voltage level, high level (single ended)		0.0		V
characteristics at ambient temperature.	VIL	Input voltage level, low level (single ended)		-0.9		V
2. In case of single- ended input, the unused pad must be tied to	VINDC	DC input voltage (with DC-coupled input) (2)		-0.45		V
VINDC. 3. In case of single-	VOUT	Data output voltage amplidude (3)	0.8	0.9	1.0	V
ended output, the unused pad must be	TR	Output rise time (20% – 80%)		25		ps
terminated with 50 ohms to ground.	TF	Output fall time (20% – 80%)		23		ps
4. Refer to timing diagram.	TDH	Output delay low-high transition (4)		300		ps
diagram.	TDL	Output delay high-low transition (4)		300		ps

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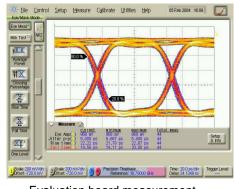
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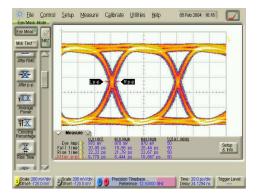


Electrical Characteristics	Symbol	Parameters	Min.	Тур.	Max.	Units
(cont.)	T _{ADJ}	Output phase delay adjustment ⁽⁴⁾		100		ps
	F _{MAX}	Maximum clock frequency		10.7		GHz
	J _{drms}	Jitter RMS degradation		1.5		ps
	I _{EE}	Power supply current		330		mA
et4U.com	P _D	Power dissipation $J_{drms} = \sqrt{J_{meas}^2 - J_{thru}^2}$		1.65		W

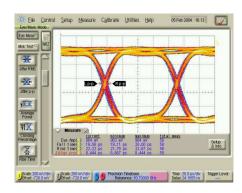
Eye Diagram Performance

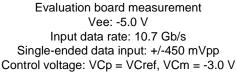


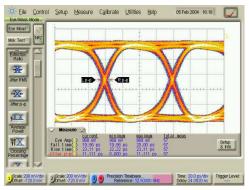
Evaluation board measurement Vee: -5.0 V Input data rate: 10.7 Gb/s Single-ended data input: +/-450 mVpp Control voltage: VCp = VCref, VCm =- 2.2 V



Evaluation board measurement Vee: -5.0 V Input data rate: 12.5 Gb/s Single-ended data input: +/-450 mVpp Control voltage: VCp = VCref, VCm =- 2.2 V







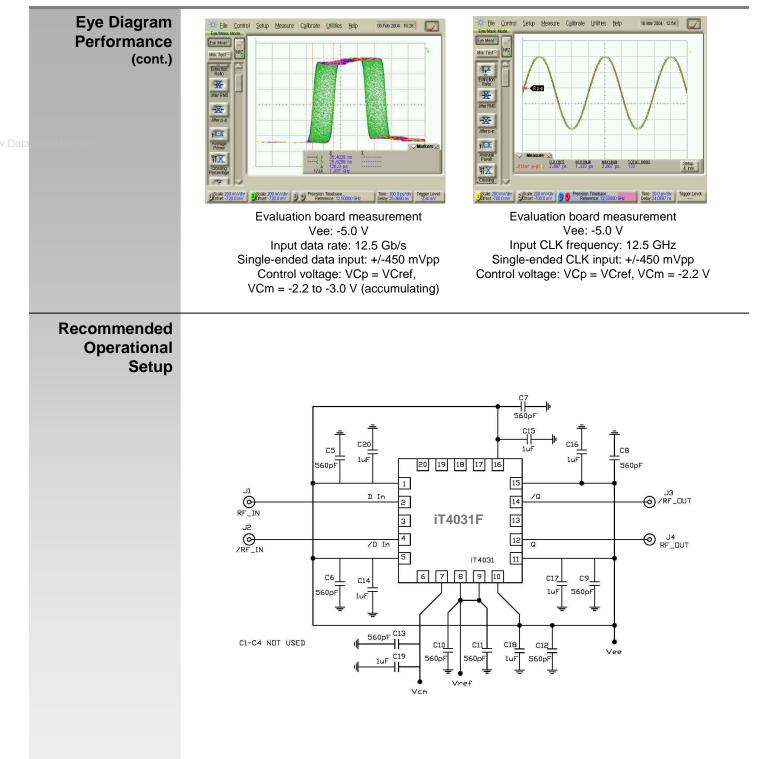
Evaluation board measurement Vee: -5.0 V Input data rate: 12.5 Gb/s Single-ended data input: +/-450 mVpp Control voltage: VCp = VCref, VCm = -3.0 V

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"F" Package Drawing, Pinouts, and Marking

Notes:

Dimensions in inches (mm) Tolerances are ± 0.0039 in. (0.100 mm)

Package drawing encompasses JEDEC MO-220 Version VHHC-2

See iTerra Application Note 10 for recommended pad layout. RoHS parts are backward compatible if application note pad layout is followed.

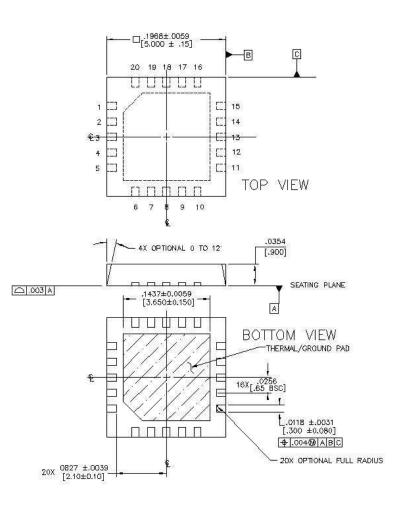
Lead frame material is copper alloy

Mold compound is UL94V0 compliant

Lead finish is NiPdAu

Marking Information iTerra MMMMFA XXNNNN LLYYWW

Where MMMM = part number F = Package Type A = Temp. Range XX = Wafer Lot NNNN=Ser. No. LLYYWW = MFG D/C



	Pinouts
P1: Vee P2: Din P3: N/C P4: Din/ P5: Vee P6: N/C P7: VCm P8: VCp P9: Vcref	P11: Vee P12: Dout P13: N/C P14: Dout/ P15: Vee P16: Vee P16: Vee P17: N/C P18: N/C P19: N/C
P10: Vee	P20: N/C

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